

REMARKS

Claim 5 has been amended and claim 6 cancelled without prejudice. No new matter has been added by virtue of the amendments. For instance, support for the amendment of claim 5 appears e.g. in the original claims of the application.

Claims 5-11 were rejected under 35 U.S.C. 102(e) over Nagai et al. (U.S. Patent 6,709,563).

While Applicants disagree with the rejection, a Rule 131 Declaration is being submitted under separate cover, which will antedate the citation.

Claims 5 and 8 were rejected under 35 U.S.C. 102(e) over newly cited Krishnamoorthy et al. (U.S. Patent 6,319,387).

While Applicants also disagree with this rejection, independent claim 5 (the only rejected independent claim) has been amended to incorporate features of claim 6. Claim 6 was not rejected over the cited document.

In view thereof, reconsideration and withdrawal of the rejection are requested.

Claims 6, 7 and 9-11 were rejected under 35 U.S.C. 103 over Krishnamoorthy et al. (U.S. Patent 6,319,387) in view of Florio et al. (U.S. Patent 5,858,198). As grounds for the rejection, it is stated that the Florio document discloses use of triethanolamine and based on that disclosure it would have been obvious to substitute triethanolamine into the process reported by Krishnamoorthy et al. The rejection is traversed.

The Florio patent states the following at column 4, lines 23-28:

The present invention is directed to an improved process for the direct electroplating of a planar substrate having openings passing therethrough, such as a printed circuit board substrate, using a dispersion of carbon black or graphite particles, hereinafter referred to collectively as a carbonaceous coating or a carbonaceous dispersion.

In describing a carbonaceous dispersion composition, the Florio document reports incorporation of a copper complexing agent into the carbonaceous dispersion composition. Thus, at column 8, lines 32-38, the florio patent discloses the following:

Another useful additive to the dispersion is a copper etchant or complexing agent compatible at the pH of the carbonaceous dispersion. This additive is used to etch copper cladding simultaneously with the formation of the carbonaceous coating and, combined with the steps described below, ensures ready removal of carbonaceous coating from the copper surfaces.

Respectfully, contrary to the position advanced in the Office Action, no incentive would have existed to utilize a component of a carbonaceous dispersion that is utilized on a printed circuit board as reported in the Florio document in a copper plating composition as reported in Krishnamoorthy et al.

In view thereof, reconsideration and withdrawal of the rejection are requested.

It is believed the application is in condition for immediate allowance, which action is earnestly solicited.

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U.S.S.N. 10/078,766
Page 6

Respectfully submitted,



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